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PRELIMINARY

ISO 9002
Registered

MSISAM27LS00

256-Bit TTL Compatible CMOS RAM

DISTINCTIVE CHARACTERISTICS

- High Speed
- Internal CMOS Circuitry for Optimum Performance over temperature and voltage
- Available with Tri-state outputs

GENERAL DESCRIPTION

The MSISAM27LS00 is a fully decoded CMOS Static Random Access Memory implemented in 1.2 μ m technology. This is fully compatible with the bipolar AM27LS00 but offers significant improvement in speed and power dissipation. The MSISAM27LS00 is organised as 256-words by 1 bit memory with an 8-bit binary address field and separate data in and data out lines. The memory has 3 active LOW chipselect inputs and threestate outputs. All inputs are buffered to present an input load of 0.5 TTL unit loads

Read/Write operation is controlled by an active LOW write enable input. When the write-enable is LOW and the chip is selected the data in the data input pin is written into the location specified by the address inputs. The output is disabled during the period nWE is LOW. READ operation is done by having the chip selected and nWE high. Data stored in the location specified by the address inputs is read out and appears at the Data Output pin.

MODE SELECT TABLE

nCS	Input nWE	DI	Data Output Status DO(tn+1)	Mode
X	X	X	Output Disabled	No Selection
L	L	L	Disabled	Write "0"
L	L	H	Disabled	Write "1"
L	H	X	Selected Bit	Read

H = HIGH

L = LOW

X = DON'T CARE

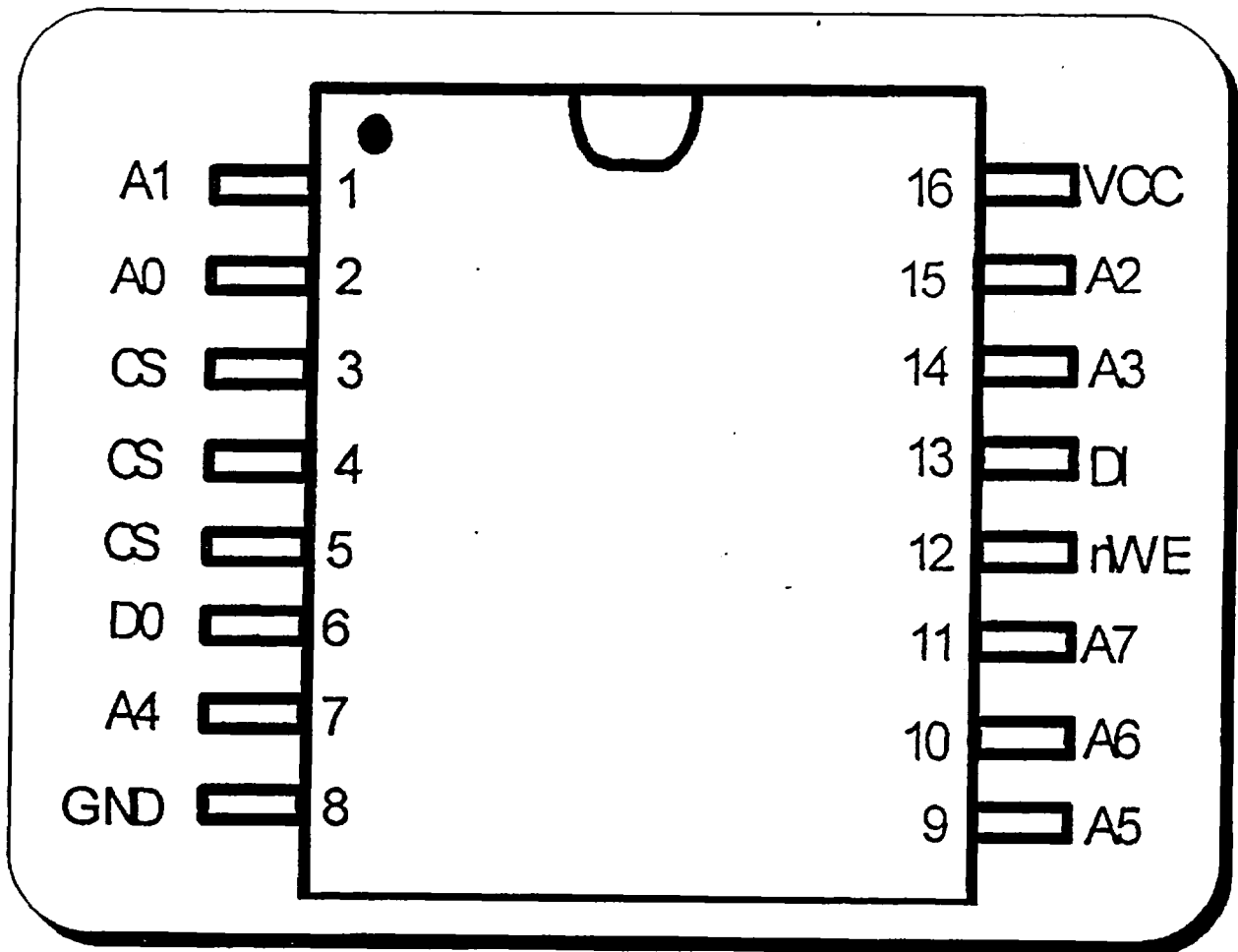
PRODUCT SELECTOR GUIDE

Part Number	MSISAM27LS00APC	MSISAM27LS00PC
Access time	35 ns	45 ns
Temperature range	0-70 deg C	0-70 deg C

Note: For burn-in order with "B" as the last letter after PC and APC

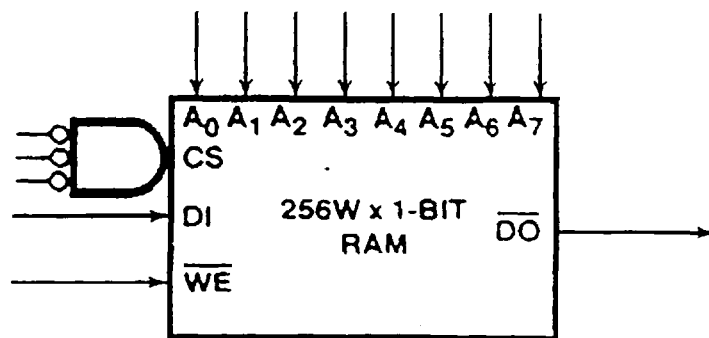
MSIS003

CONNECTION DIAGRAM



Notes: Pin 1 Marked for orientation.
CS & nWE are true when LOW.

LOGIC SYMBOL



LS300201

VCC = Power Supply
GND = Ground

ABSOLUTE MAXIMUM RATINGS

OPERATING RANGES

Storage Temperature----- -55 to +150 °C
 Ambient Temperature
 with Power Applied----- -10 to +85 °C
 Supply Voltage to Ground potential
 (pin 16 to pin 8 continuous)----- -0.5 V to +7.0 V
 DC Voltage applied to Outputs
 for High Output state----- -0.5V to V_{CC}^{max}
 DC Input Voltage----- -0.5V to V_{CC}
 Output Current, into outputs----- 30 ma
 DC Input Current----- -30 ma to +5 ma

Temperature----- 0 to 70 °C
 Supply Voltage----- +4.75 V to 5.25 V
 Operating ranges define those limits between
 which functionality of the device is guaranteed

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits are not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

DC CHARACTERISTICS (over operating range unless otherwise specified)

Parameter Symbol	Parameter Description	Test Conditions	Min	Tyo (Note 1)	Max	Units
V_{OH}	Output High Voltage	$V_{CC} = \text{Min}$ $V_{in} = V_{IH}$ or V_{IL} $I_{OH} = -5.2 \text{ ma}$	2.4	3.2		Volts
V_{OL}	Output Low Voltage	$V_{CC} = \text{Min}$ $V_{in} = V_{IH}$ or V_{IL} $I_{OL} = 16 \text{ ma}$		0.3	0.45	Volts
V_{IH}	Input HIGH Voltage	Guaranteed Input logical HIGH Voltage for all inputs	2			Volts
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all inputs			0.8	Volts
I_{IH}	Input High Current	$V_{CC} = \text{Max}$, $V_{in} = 2.7V$		<1	20	μA
I_{IL}	Input Low Current	$V_{CC} = \text{Max}$, $V_{in} = 0.40V$		< 1 μA	-0.25	mA
I_{SC} (Note 2)	Output Short Circuit Current	$V_{CC} = \text{Max}$, $V_{out} = 0.0V$	-40	-90	-150	mA
I_{CC}	Power Supply Current	All Inputs = Gnd $V_{CC} = \text{Max}$ 'A' Version Standard		< 1 <1	115 70	mA
V_{CL}	Input Clamp Voltage	$V_{CC} = \text{Min}$, $I_{in} = -18mA$		-0.850	-1.2	Volts
I_{CEX}	Output Leakage Current	$V_{CS} = V_{IH}$, or $V_{nWE} = V_{IL}$, $V_{OUT} = 2.4V$ $V_{CS} = V_{IH}$, or $V_{nWE} = V_{IL}$, $V_{OUT} = 0.4V$, $V_{CC} = \text{Max}$ (Note 2)	-30	0 0	30	μA μA

Notes: 1. Typical limits are at $V_{CC} = 5.0V$ and $T_A = 25 \text{ Deg.C}$

2. This applies to three state devices only.

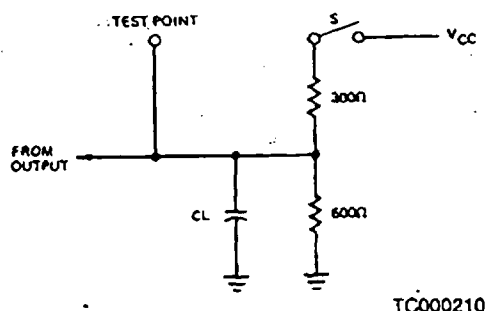
3. These are absolute voltages with respect to device ground pin and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.

4. Operating Specification with adequate time for temperature stabilisation and transverse air flow exceeding 400 linear feet per minute.

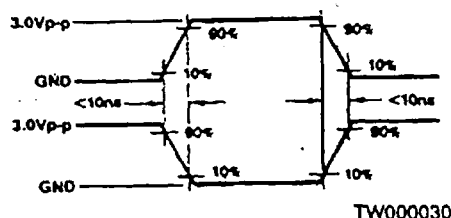
Conformance testing performed instantaneously where $T_A = T_C = T_J = 0JA = 44-59 \text{ Deg. c/w}$ (with moving air) for ceramic DIPs.

$0JC = 10-170 \text{ c/w}$ for flat pack or leadless chip carriers.

SWITCHING TEST* CIRCUIT



SWITCHING TEST WAVEFORM



KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

SWITCHING CHARACTERISTICS (Over operating Range unless otherwise specified)

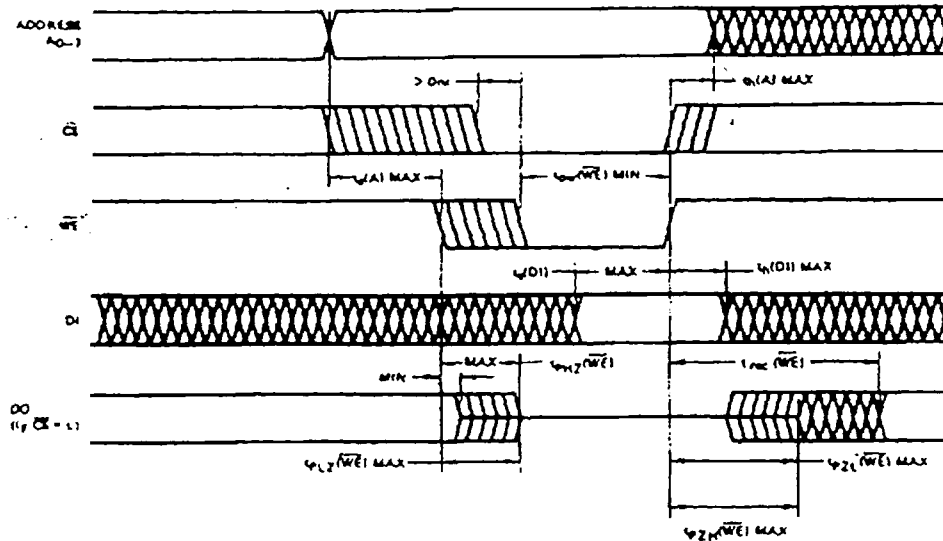
No	Parameter Symbol	Parameter Description	MSIS27C00 A Min	Max	MSIS27C00 Min	Max	Units
1	tPLH	Delay from Address to output		35		45	nS
2	tPHL						
3	tPZH(nCS) tPZL (nCS)	Delay from chip selcet(LOW) to Active output and correct data		25		25	ns
4	tPZH(nWE) tPZL (nWE)	Dealy from write enable (HIGH) to Active output and Correct data		35		45	ns
5	t _s (A)	Setup Time Address(Prior to Initiation of Write)	0		0		ns
6	t _h (A)	Hold time address(after termination of Write)	0		0		ns
7	t _s (DI)	Setup Time Data Input (Prior to termination of Write)	25		30		ns
8	t _h (DI)	Hold Time Data Input (After termination of Write)	0		0		ns
9	t _{pw} ((nWE)	Minimum Write Eanble Pulse Width to Inusre Write	25		30		ns
10	tPHZ(nCS) tPLZ(nCS)	Delay from Chip Select (HIGH) to inactive Output (Hi-Z)		25		25	ns
12	tPLZ(nWE) tPHZ(nWE)	Dealy from Write Eanble (LOW) to inactive Output (Hi-Z)		30		30	ns

Notes:

- Typical inputs are at VCC=5.0V and TA=25 °C
- Output is preconditioned to insure corrcet data is present on al outputs when write is terminated (No write recovery Glitch)
- tPLH(A) and tPHL(A) are tested with S (switch) closed and CL=50pF with both input and output timing referenced to 1.5 V
- tPZH(nWE) and tPZH9NCS) are measured with S open, CL=50pF and both input and output timing referenced to 1.5 V. tPZL(nWE) and tPZL(nCS) are measured with S closed, CL=50pF and both input and output timing referenced to 1.5 V. tPHZ(nV) and tPHZ(nWE) are measured with S open , CL < or = 5pF and are measured between the 1.5 V level on the input and VOH-500 mV level on the output. tPLZ(nWE) and tPLZ(nCS) are measured with S closed and CL < or = and are measu between the 1.5 V level on the input and VOL + 500 mV on the output

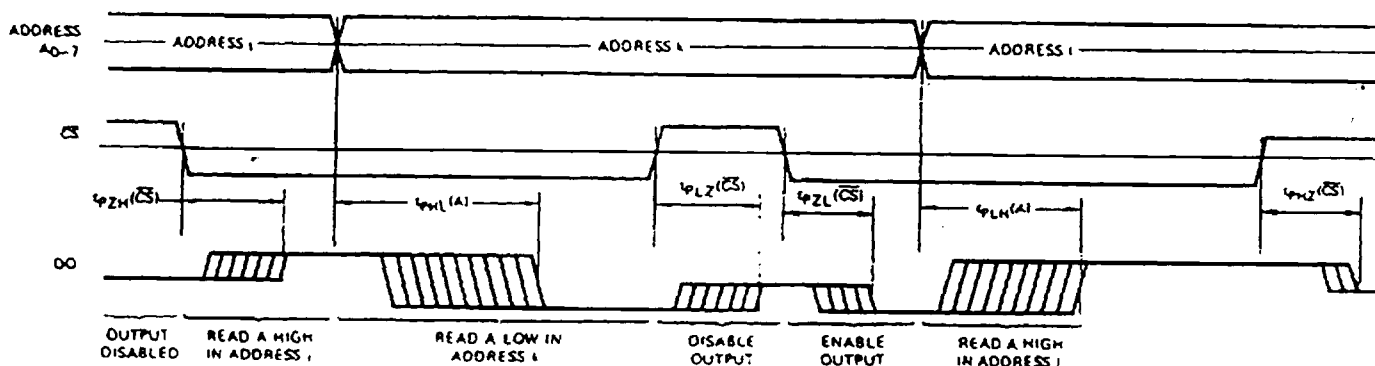
SWITCHING WAVEFORMS

WRITE MODE



Write cycle timing: The cycle is initiated by an address change. After $t_{s(A)}$ max, the write cycle may begin. The chip select must be LOW for writing. Following the write pulse $t_{h(A)}$ max must be allowed before the address may be changed again. The output will be inactive (floating at tristate) while the Write Enable is LOW. Ordinarily, the chip select should be LOW during the entire write pulse.

READ MODE



Switching delays from address and chip select inputs to the data output. For the MSIS27C00 / 00A the disabled output is "OFF" represented by a single centerline.